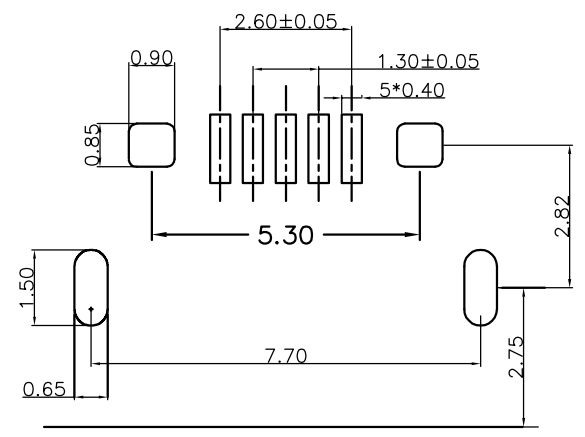
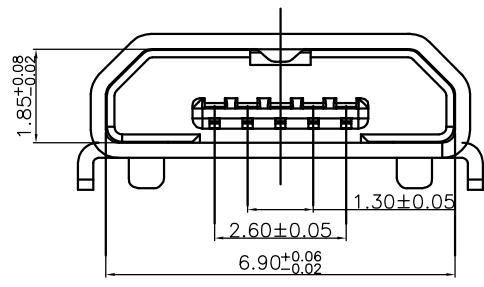
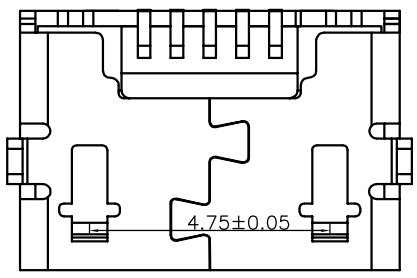
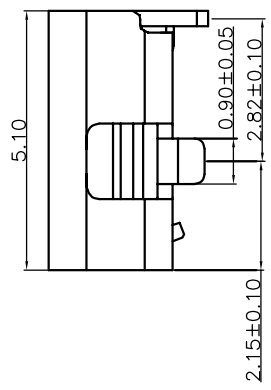
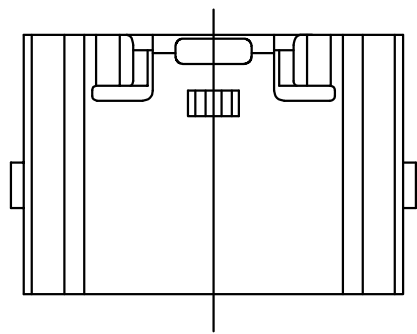
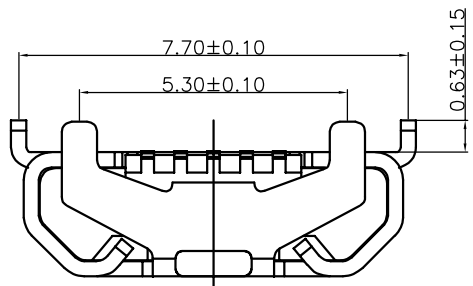


REV.	ECN.NO.	APPD.
A0	/	/



PCB LAYOUT

Note:

1.Material:

- 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
- 1.2 Contact: copper alloy,t=0.15mm
- 1.3 Shell: copper alloy&SUS

2.Specification:

- 2.1 Current rating: 1 A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 30 mΩ Max.
- 2.4 Insulation resistance: 100 MΩ Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.after 10000 insertion/extraction cycles
- 2.7 Temperature range: -30°C~80°C

U442-501X-XXX0X8

- 1: 铁壳镀镍
- 5: 铜壳镀镍
- 4: 铁壳镀金
- 6: 铜壳镀雾锡
- 8: 铜壳镀金
- 1: 半金1u"
- 3: 半金3u"
- G: 半金G/Fu"
- 1: 吸塑盒
- 8: 载带
- 1: 黑色
- 2: 白色
- 3: 米黄色
- 1: PA66
- 2: PBT
- 6: LCP

TOLERANCE UNLESS OTHERWISE SPECIFIED		FLW 深圳市华联威电子科技有限公司				
.XXX ±0.10		HUA LIAN WEI TECHNOLOGY ELECTRONICS CO;LTD.				
.XX ±0.20		.X' ±3'				
.X ±0.30		.XX' ±2'				
APPROVED		PART NAME:	MICRO 5P/F 牛角无卷边反向			
CHECKED		PART No:	U442-5016-X61038		C	
DRAWN	weihong	PROJECTION:	UNIT:	SCALE	SHEET	REV.
DATE	2021. 10. 6		mm	1:1	10F1	A0